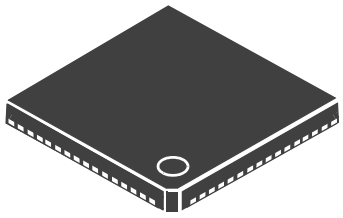
Document order number: MPC18730
Rev 1.0, 10/2005

Power Management IC with Five Regulated Outputs Programmed Through 3-Wire Serial Interface

18730

POWER MANAGEMENT IC



EP SUFFIX
98ARL10571D
64-TERMINAL 0.5 mm PITCH
QFN

The MPC18730 Power Management IC (PMIC) regulates five independent output voltages from either a single cell Li-Ion (2.7 V to 4.2 V input range) or from a single cell Ni-MH or dry cell (0.9 V to 2.2 V input range).

The PMIC includes 2 DC-DC converters and 3 low drop out (LDO) linear regulators. The output voltage for each of the 5 output voltages is set independently through a 3-wire serial interface. The serial interface also configures the PMIC's versatile start-up control system, which includes multiple wakeup, sleep, standby, and reset modes to minimize power consumption for portable equipment.

In single cell Li-Ion applications two DC-DC converters are configured as buck (step-down) regulators. In single cell Ni-MH or dry cell applications, one DC-DC converter is configured as a boost (step-up) regulator, and the other as buck-boost regulator. The DC-DC converters' output voltages have set ranges 1.613 V to 3.2 V at up to 120 mA, and 0.805 V to 1.5 V up to 100 mA through the serial interface.

ORDERING INFORMATION		
Device	**Temperature Range (T_A)**	**Package**
MPC18730EP/R2	-10°C to 65°C	64 QFN

PRELIMINARY*

Features

- Operates from single cell Li-Ion, Ni-MH, or Alkaline
- 2 DC-DC Converters
- 3 Low Drop Regulators
- Serial Interface Sets Output Voltages
- 4 Wake Inputs
- Low Current Standby Mode
- Pb-Free Packaging Designated by Suffix Code EP

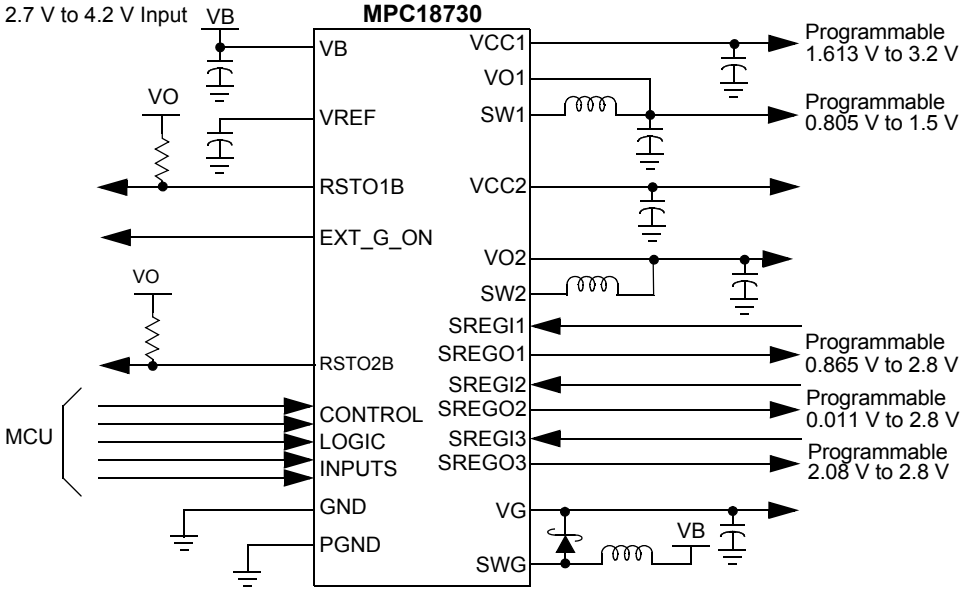


Figure 1. MPC18730 Simplified Application Diagram

* This document contains information on a product under development.
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INTERNAL BLOCK DIAGRAM

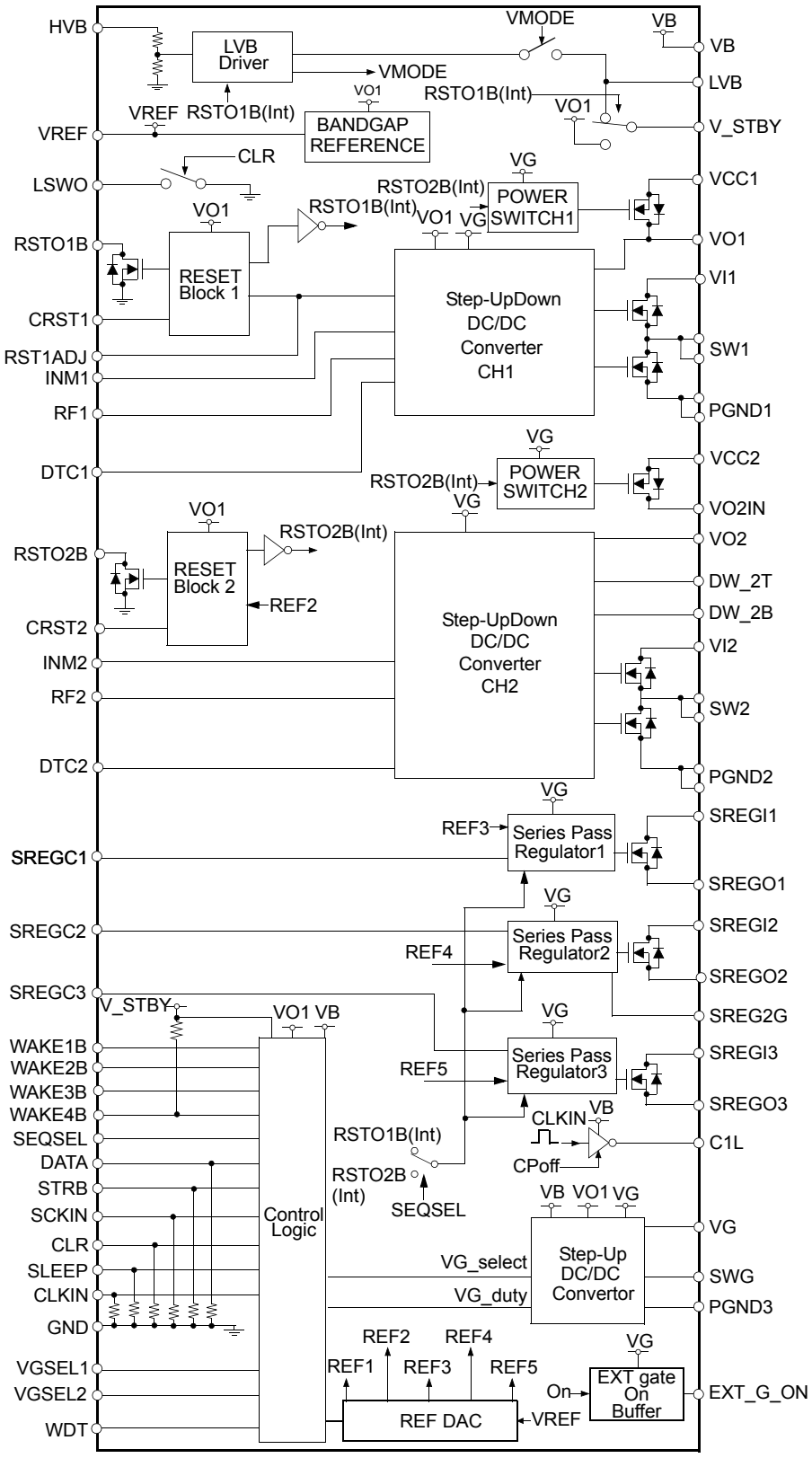


Figure 2. MPC18730 Simplified Internal Block Diagram

TERMINAL CONNECTIONS

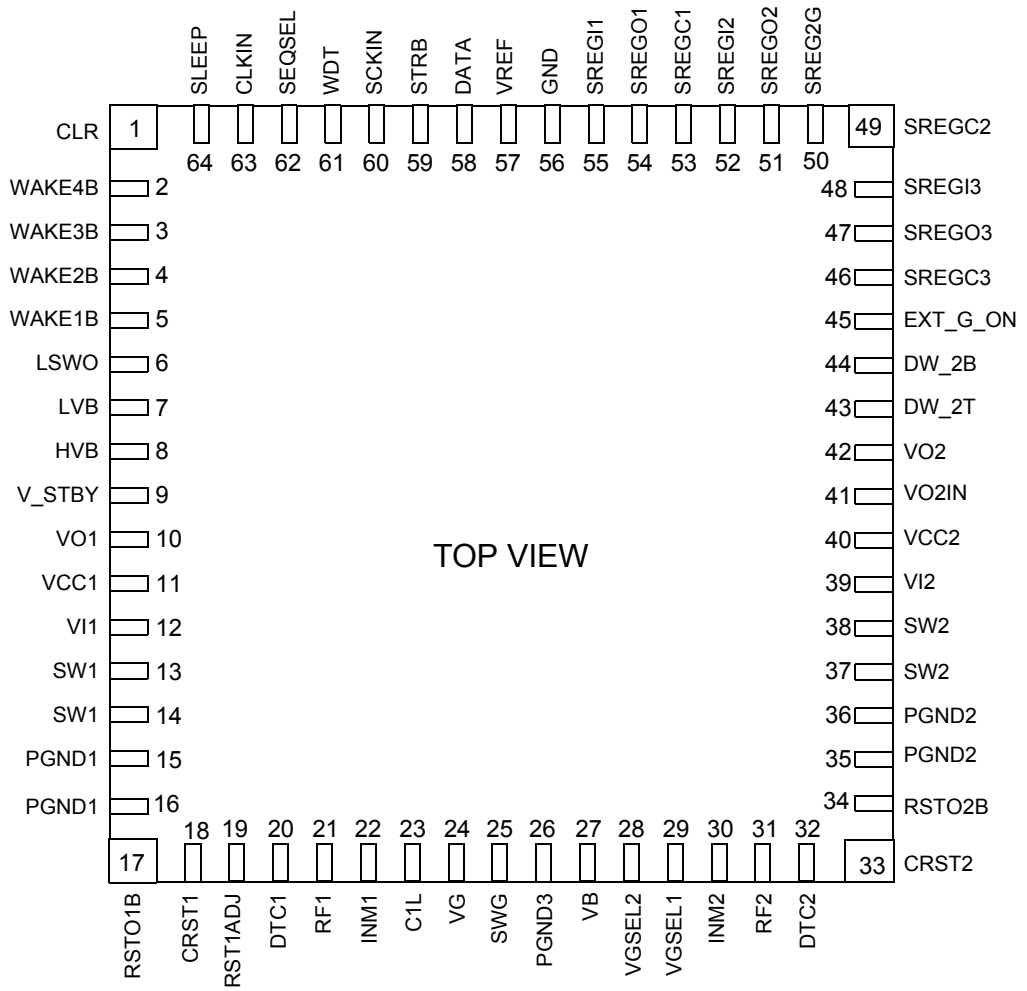


Figure 3. MPC18730 Terminal Connections

Table 1. MPC18730 Terminal Definitions

A functional description of each terminal can be found in the Functional Terminal Description section beginning on page 14.

Terminal Number	Terminal Name	Terminal Function	Formal Name	Definition
1	CLR	Input	Clear	Start-up Signal Input Latch/Clear
2	WAKE4B	Input	Wake Signal 4	Start-up Signal Input 4
3	WAKE3B	Input	Wake Signal 3	Start-up Signal Input 3
4	WAKE2B	Input	Wake Signal 2	Start-up Signal Input 2
5	WAKE1B	Input	Wake Signal 1	Start-up Signal Input 1
6	LSWO	Output	Low-Side Switch Output	Low-Side Switch Output Terminal
7	LVB	Input	Low Voltage Battery	VB Power Supply Connection for Ni_mh
8	HVB	Input	High Voltage Battery	VB Power Supply Connection for Li_ion
9	V_STBY	Output	Standby Voltage	V_STBY Voltage Output

Table 1. MPC18730 Terminal Definitions (continued)

A functional description of each terminal can be found in the Functional Terminal Description section beginning on page 14.

Terminal Number	Terminal Name	Terminal Function	Formal Name	Definition
10	VO1	Input	Voltage Input 1	Switching Power Supply Circuit 1, VO1 Voltage Input, VO1 Power Supply
11	VCC1	Output	Voltage Output 1	Power Switch 1 Output
12	VI1	Output	Voltage Output 1	Switching Power Supply Circuit 1 Output
13	SW1	Power	Switching 1	Switching Power Supply Circuit 1 Coil Connection
14	SW1	Power	Switching 1	Switching Power Supply Circuit 1 Coil Connection
15	PGND1	Ground	Power Ground 1	Switching Power Supply Circuit 1 Power GND
16	PGND1	Ground	Power Ground 1	Switching Power Supply Circuit 1 Power GND
17	RSTO1B	Output	Inverted Reset Output 1	Reset Circuit 1 Reset Signal Output
18	CRST1	Input	Reset Delay Capacitor 1	Reset Circuit 1 Reset Signal Delaying Capacitor Connection
19	RST1ADJ	Output	Reset1 Adjustment	Switching Power Supply Circuit 1 Reset Voltage Reference Output
20	DTC1	Power	Duty Control	Switching Power Supply Circuit 1 Maximum Duty Setting
21	RF1	Output	Reference Feedback 1	Switching Power Supply Circuit 1 Error Amp Output
22	INM1	Input	Input Minus 1	Switching Power Supply Circuit 1 Error Amp Inverse Input
23	C1L	Power	Charge Pump Capacitor	VG Power Supply Circuit Charge Pump Capacitor Connection
24	VG	Output	Gate Voltage	VG Power Supply Circuit Voltage Output, Pre-Diver Circuit Power Supply
25	SWG	Power	Switching	VG Power Supply Circuit Coil Connection
26	PGND3	Ground	Power Ground 3	VG Power Supply Circuit Power GND
27	VB	Power	Battery Voltage	VB Power Supply Connection
28	VGSEL2	Output	VG Select 2	VG Power Supply Circuit Output Voltage Setting 2
29	VGSEL1	Output	VG Select 1	VG Power Supply Circuit Output Voltage Setting 1
30	INM2	Input	Input Minus	Switching Power Supply Circuit 2 Error Amp Inverting Input
31	RF2	Output	Reference Feedback 2	Switching Power Supply Circuit 2 Error Amp Output
32	DTC2	Power	Duty Control	Switching Power Supply Circuit 2 Maximum Duty Setting
33	CRST2	Input	Reset Delay Capacitor 1	Reset Circuit 2 Reset Signal Delay Capacitor Connection
34	RSTO2B	Output	Inverted Reset Output 2	Reset Circuit 2 Reset Signal Output
35	PGND2	Ground	Power Ground 2	Switching Power Supply Circuit 2 Power GND
36	PGND2	Ground	Power Ground 2	Switching Power Supply Circuit 2 Power GND
37	SW2	Power	Switching	Switching Power Supply Circuit 2 Coil Connection
38	SW2	Power	Switching	Switching Power Supply Circuit 2 Coil Connection
39	VI2	Output	Voltage Output	Switching Power Supply Circuit 2 Output
40	VCC2	Output	Voltage Output	Power Switch 2 Output
41	VO2IN	Input	Voltage Input	Power Switch 2 Voltage Input
42	VO2	Input	Voltage Input	Switching Power Supply Circuit 2 VO2 Voltage Input

Table 1. MPC18730 Terminal Definitions (continued)

A functional description of each terminal can be found in the Functional Terminal Description section beginning on page 14.

Terminal Number	Terminal Name	Terminal Function	Formal Name	Definition
43	DW_2T	Output	Step Down Top FET 2	Switching Power Supply Circuit 2 Step down Top side FET Gate Output for Ni_mh
44	DW_2B	Output	Step Down Bottom FET 2	Switching Power Supply Circuit 2 Step down Bottom side FRT Gate Output for Ni_mh
45	EXT_G_ON	Output	Gate Switch	External Transistor Gate Signal Output
46	SREGC3	Power	Regulator Capacitor 3	Series Pass Power Supply Circuit 3 External Feedback Connection
47	SREGO3	Output	Regulator Output 3	Series Pass Power Supply Circuit 3 Output
48	SREGI3	Power	Regulator Input 3	Series Pass Power Supply Circuit 3 Power Supply
49	SREGC2	Power	Regulator Capacitor 2	Series Pass Power Supply Circuit 2 External Feedback Connection
50	SREG2G	Output	Regulator Gate Output 2	Series Pass Power Supply Circuit 2 External Transistor Gate Signal Output
51	SREGO2	Output	Regulator Output 2	Series Pass Power Supply Circuit 2 Output
52	SREGI2	Power	Regulator Input 2	Series Pass Power Supply Circuit 2 Power Supply
53	SREGC1	Power	Regulator Capacitor 1	Series Pass Power Supply Circuit 1 External Feedback Connection
54	SREGO1	Output	Regulator Output 1	Series Pass Power Supply Circuit 1 Output
55	SREGI1	Power	Regulator Input 1	Series Pass Power Supply Circuit 1 Power Supply
56	GND	Ground	Ground	GND
57	VREF	Output	Reference Voltage	Reference Voltage Output
58	DATA	Input	Data Signal	Serial Interface Data Signal Input
59	STRB	Input	Strobe	Serial Interface Strobe Signal Input
60	SCKIN	Input	Serial Clock	Serial Interface Clock Signal Input
61	WDT	Input	Watch Dog Timer	Watchdog Timer Capacitor Connection
62	SEQSEL	Input	Sequence Input	Start-Up Sequence Setting Input
63	CLKIN	Input	Clock Input	External Synchronous Clock Signal Input
64	SLEEP	Input	Sleep Signal	Sleep Signal Input

MAXIMUM RATINGS

Table 2. Maximum Ratings

All voltages are with respect to ground unless otherwise noted. Exceeding these ratings may cause a malfunction or permanent damage to the device.

Ratings	Symbol	Value	Unit
ELECTRICAL RATINGS			
Power Supply Voltage	V_B	-0.5 to 5.0	V
Analog Signal Input (1)	V_{INAN}	-0.5 to VO1+0.5	V
Logic Signal Input			V
WAKE1~4B	V_{ILRSTB}	-0.5 to V_STBY+0.5	
CLR, SLEEP, CLKIN, SCKIN, DATA, STRB	V_{ILGC}	-0.5 to VO1+0.5	
VGSEL1,2	V_{ILGSEL}	-0.5 to VB+0.5	
Output Power Current			mA
V_{CC1} Power Supply Circuit (2)	I_{OVO1}	120	
V_{CC2} Power Supply Circuit	I_{OVO2}	100	
SREG1 Power Supply Circuit	I_{OREG1}	80	
SREG2 Power Supply Circuit	I_{OREG2}	100	
SREG3 Power Supply Circuit	I_{OREG3}	80	
VG Power Supply Circuit	I_{OVG}	8	
RSTO1B Power Supply Circuit	I_{ORSTB}	-20	
Open-Drain Output Apply Voltage			V
RSTO1B	V_{IODR}	-0.5 to 3.3	
LSWO	V_{IODV}	-0.5 to 3.3	
ESD Voltage			V
Human Body Model (HBM) (3)	V_{ESD1}	±1500	
Machine Model (MM) (4)	V_{ESD2}	± 200	
Charge Device Model (CDM)	V_{CDM}	± 750	
THERMAL RATINGS			
Operating Temperature			°C
Ambient	T_A	-10 to 65	
Junction	T_J	150	
Storage Temperature	T_{STG}	-50 to 150	°C
Thermal Resistance (5) Junction to Ambient	$R_{\theta JA}$	69	°C/W
Lead Soldering Temperature(6)	T_{SOLDER}	260	°C

Notes

1. VREF, DTC1, DTC2, SREGC1, SREGC2, SREGC3 and RST1ADJ.
2. Includes the series pass power supply circuit output current.
3. ESD1 testing is performed in accordance with the Human Body Model (C_{ZAP} = 100 pF, R_{ZAP} = 1500 Ω).
4. ESD2 testing is performed in accordance with the Machine Model (C_{ZAP} = 200 pF, R_{ZAP} = 0 Ω) and in accordance with the system module specification with a capacitor 0.01 μF connected from OUT to GND.
5. Device mounted on a 2s2p test board, in accordance with JEDEC JESD51-6 and JESD51-7.
6. Terminal soldering temperature limit is for 10 seconds maximum duration. Not designed for immersion soldering. Exceeding these limits may cause malfunction or permanent damage to the device.

STATIC ELECTRICAL CHARACTERISTICS

Table 3. Static Electrical Characteristics

Characteristics noted under conditions V_B = 1.2 V, V_{O1} = 2.4 V, V_G = 6.0 V, f_{CLK} = 176.4 kHz unless otherwise noted. Typical values noted reflect the approximate parameter means at T_A = 27°C under nominal conditions unless otherwise noted.

Characteristic	Symbol	Min	Typ	Max	Unit
GENERAL					
VB Power Supply Voltage					V
Power Supply Voltage 1	V_{LVB}	0.9	1.2	2.2	
Power Supply Voltage 2	V_{HVB}	2.7	3.5	4.2	
Series Regulator Input Voltage (7), (8)	V_{SREGI}	V_{SREG}+0.2(9)	V_{SREG}+0.3	V_{SREG}+0.4	V
Start-Up Voltage	V_{BST}	0.9	-	-	V
Analog Signal Input (10)	V_{IANA}	0	-	V_{O1}	V
Logic Signal Input					V
RSTO1 ~ 4B	V_{ILRSTB}	0	-	V_STBY	
CLR, SLEEP, CLKIN, DATA, STRB and SCKIN	V_{ILGC}	0	-	VO1	
VGSEL1, 2	V_{ILGSEL}	0	-	VB	
Output Power Current					mA
V_{CC1} Power Supply Circuit (11)	I_{OVCC1}	0	-	100	
V_{CC2} Power Supply Circuit (11)	I_{OVCC2}	0	-	80	
SREG1 Power Supply Circuit	I_{OSREG1}	5	-	60	
SREG2 Power Supply Circuit	I_{OSREG2}	6	-	80	
SREG3 Power Supply Circuit	I_{OSREG3}	5	-	60	
VG Power Supply Circuit	I_{OVG}	0	-	6	
RSTO	I_{ORSTB}	-5	-	0	
Supply Current in Stand-by mode					
VB Supply Current (VB = 1.2 V for Ni_MH)	I_{BSNi}	-	5	10	mA
(HVB = 3.5 V for Li-Ion)	I_{BSLi}	-	8	12	
Supply Current in Operating mode					mA
VB Supply Current (VB = 1.2 V for Ni_MH)	I_{BNi}	-	9	18	
(HVB = 3.5 V for Li-Ion)	I_{BLi}	-	7	14	
Reference Power Supply Circuit					
Output Voltage	V_{REF}	1.255	1.275	1.295	V
Output Current	I_{OREF}	-0.3	-	0.3	mA
Switching Power Supply 1	V_{CC1}	2.3	2.4	2.5	V
V_{CC1} Output Voltage (I_o = 0~100 mA)					

Notes

7. When applying voltage from an external source.
8. 0.3 V when VG is 4.5 V.
9. Provide 2 V or higher for the voltage difference (VG - VO1).
10. VREF, DTC1, DTC2, SREGC1, SREGC2, SREGC3 and RST1ADJ.
11. Includes the series pass power supply circuit output current.

This paragraph is boilerplate - you may add to it but, can not change wording. You may change numeric values

Table 3. Static Electrical Characteristics (continued)

Characteristics noted under conditions V_B = 1.2 V, V_{O1} = 2.4 V, V_G = 6.0 V, f_{CLK} = 176.4 kHz unless otherwise noted. Typical values noted reflect the approximate parameter means at T_A = 27°C under nominal conditions unless otherwise noted.

Characteristic	Symbol	Min	Typ	Max	Unit
Switching Power Supply 2					V
V_{CC2} Output Voltage (I_o = 0~80 mA)	V_{CC2}	1.05	1.15	1.25	
DW_2T Output Voltage (12) (I_{source} = 400 μA)	V_{DW2TH}	5.2	-	VG	
(I_{sink} = 400 μA)	V_{DW2TL}	0	-	0.3	
DW_2B Output Voltage (12) (I_{source} = 400 μA)	V_{DW2BH}	5.2	-	VG	
(I_{sink} = 400 μA)	V_{DW2BL}	0	-	0.3	
Series Pass Power Supply Circuit					
SREG1 Control Voltage (I_o = 5~60 mA) (13)	V_{SREG1}	2.7	2.8	2.9	V
SREG1-Error AMP Input offset voltage (14)	SR1OFST	-13.5	-	24.5	mV
SREG2 Control Voltage (I_o = 6~80 mA) (13)	V_{SREG2}	2.7	2.8	2.9	V
SREG2-Error AMP Input offset voltage (15)	SR2OFST	-17	-	17	mV
SREG3 Control Voltage (I_o = 5~60 mA) (13)	V_{SREG3}	2.7	2.8	2.9	V
SREG3-Error AMP Input offset voltage (16)	SR3OFST	-11	-	23	mV
SREG2G Output Voltage (17) (I_{source} = 2.5 μA)	SREG2GH	5	-	VG	V
(I_{sink} = 2.5 μA)	SREG2GL	0	-	0.5	V
Power Switch On Resistance					Ω
V_{CC1} Circuit	R_{VCC1}	-	0.4	0.6	
V_{CC2} Circuit	R_{VCC2}	-	0.4	0.6	
VG Power Supply Circuit					V
(I_o = 0~6 mA) (18)	VG_00	5.5	6.0	6.5	
(I_o = 0~6 mA) (19)	VG_10	4.6	5.0	5.4	
C1L Output Voltage (I_{source} = 2.5 mA)	VO11LH	VB x 0.85	-	VB	
(I_{sink} = 2.5 mA)	VO11LL	0	-	0.4	
VGH Voltage (Certified value)	VGH	-	-	10.5	
V_STBY Output Voltage for Li_ion (I_o = 300 μA) (20)	V_{LVB}	1.75	-	2.45	V

Notes

12. Connect a transistor with gate capacity of 200 pF or smaller to DW_2T and DW_2B
13. If a capacitor with capacitance of 22μF is connected to SREGO, use a phase compensation capacitor between SREGO and SREGC when the load is 5 mA (6 mA for SREG2) or lower. The output voltage values shown in the table assume that external resistance is connected as follows:
    SREGI1 = 3.0V to 3.3V, 65.14KΩ between SREGO1 and SREGC1, 34.86KΩ between SREGC1 and GND.
    SREGI2 = 3.0V to 3.3V, 54.46KΩ between SREGO2 and SREGC2, 45.54KΩ between SREGC2 and GND.
    SREGI3 = 3.0V to 3.3V, 73.84KΩ between SREGO3 and SREGC3, 26.16KΩ between SREGC3 and GND.
14. Calculated by the right formula for input offset: SR1OFST=(Vref x 0.77) - (SREGO1 ÷ (100k ÷ 34.86k))
15. Calculated by the right formula for input offset: SR2OFST=(Vref x 1) - (SREGO1 ÷ (100k ÷ 45.54k))
16. Calculated by the right formula for input offset: SR3OFST=(Vref x 0.58) - (SREGO1 ÷ (100k ÷ 26.16k))
17. Connect a transistor with gate capacity of 300 pF or smaller to REG2G.
18. When VGSEL1 is Low and VGSEL2 is Low, I/O=3mA or higher is certified by specification.
19. When VGSEL1 is High and VGSEL2 is Low, I/O=3mA or higher is certified by specification.
20. When HVB is 4.2V and the load from V_STBY is 0.5μA or higher.

Table 3. Static Electrical Characteristics (continued)

Characteristics noted under conditions V_B = 1.2 V, V_{O1} = 2.4 V, V_G = 6.0 V, f_{CLK} = 176.4 kHz unless otherwise noted. Typical values noted reflect the approximate parameter means at T_A = 27°C under nominal conditions unless otherwise noted.

Characteristic	Symbol	Min	Typ	Max	Unit
Reset Circuit					
Reset Voltage 1	V_{RST1}	0.85 x VO1	0.88 x VO1	0.91 x VO1	V
Reset Voltage 2	V_{RST2}	0.80 x VO2	0.85 x VO2	0.90 x VO2	V
Hysteresis Voltage 1 (@RST1)	V_{HYRS1}	40	78	115	mV
Hysteresis Voltage 2 (@RST2)	V_{HYRS2}	50	75	100	mV
RSTB (V_{RSTB} = 2.4 V)	$I_{ORSTB1,2}$	0	-	10	μA
(I_{sink} = 2 mA)	$V_{OLRSTB1,2}$	0	-	0.5	V
CRST (I_{sink} = 100 μA)	$V_{OLCR1,2}$	0	-	0.7	V
High Level Threshold Voltage	$V_{IHCR1,2}$	1.25	1.42	1.65	V
Low Level Threshold Voltage	$V_{ILCR1,2}$	0.75	1.00	1.15	V
CRST Pull-Up Resistance	$R_{PUPRC1,2}$	50	100	150	KΩ
V_STBY Output Resistance					Ω
Output Resistance (VO1)	R_{VO1}	-	30	45	
Output Resistance (VB)	R_{VB}	-	200	400	
LSWO Output Resistance	R_{LSWO}	-	42	50	Ω
Output Resistance					
Ext_G_ON					V
Ext_G_ON Output Voltage (I_{source} = 100 μA)	V_{OHEXTG}	VG x 0.9	-	VG	
(I_{sink} = 100 μA)	V_{OLEXTG}	0	-	VG x 0.1	
Logic Input					
"H" Level Input Voltage (21)	V_{IHVS}	V_STBY - 0.2	-	-	V
"L" Level Input Voltage (21)	V_{ILVS}	-	-	0.2	V
"H" Level Input Voltage (22)	V_{IH}	1.5	-	-	V
"L" Level Input Voltage (22)	V_{IL}	-	-	0.4	V
"H" Level Input Voltage (23)	V_{IHVB}	VB - 0.2	-	-	V
"L" Level Input Voltage (23)	V_{ILVB}	-	-	0.2	V
"H" Level Input Current (21), (23)	I_{IH}	-1	-	1	μA
"L" Level Input Current (23), (24)	I_{IL}	-1	-	1	μA
Pull Up Resistance (25)	R_{PUP}	410	590	770	KΩ
Pull Down Resistance (26)	R_{PDW}	330	480	625	KΩ

Notes

21. Applied to WAKEB1 ~ 4 and SEQSEL.
22. Applied to CLR, SLEEP, CLKIN, DATA, STRB and SCKIN.
23. Applied to VGSEL1 and 2.
24. Applied to WAKEB1 ~ 3, CLR, SLEEP, CLKIN, DATA, STRB, SCKIN and SEQSEL.
25. Applied to WAKEB4.
26. Applied to CLR, SLEEP, CLKIN, DATA, STRB and SCKIN.

DYNAMIC ELECTRICAL CHARACTERISTICS

Table 4. Dynamic Electrical Characteristics

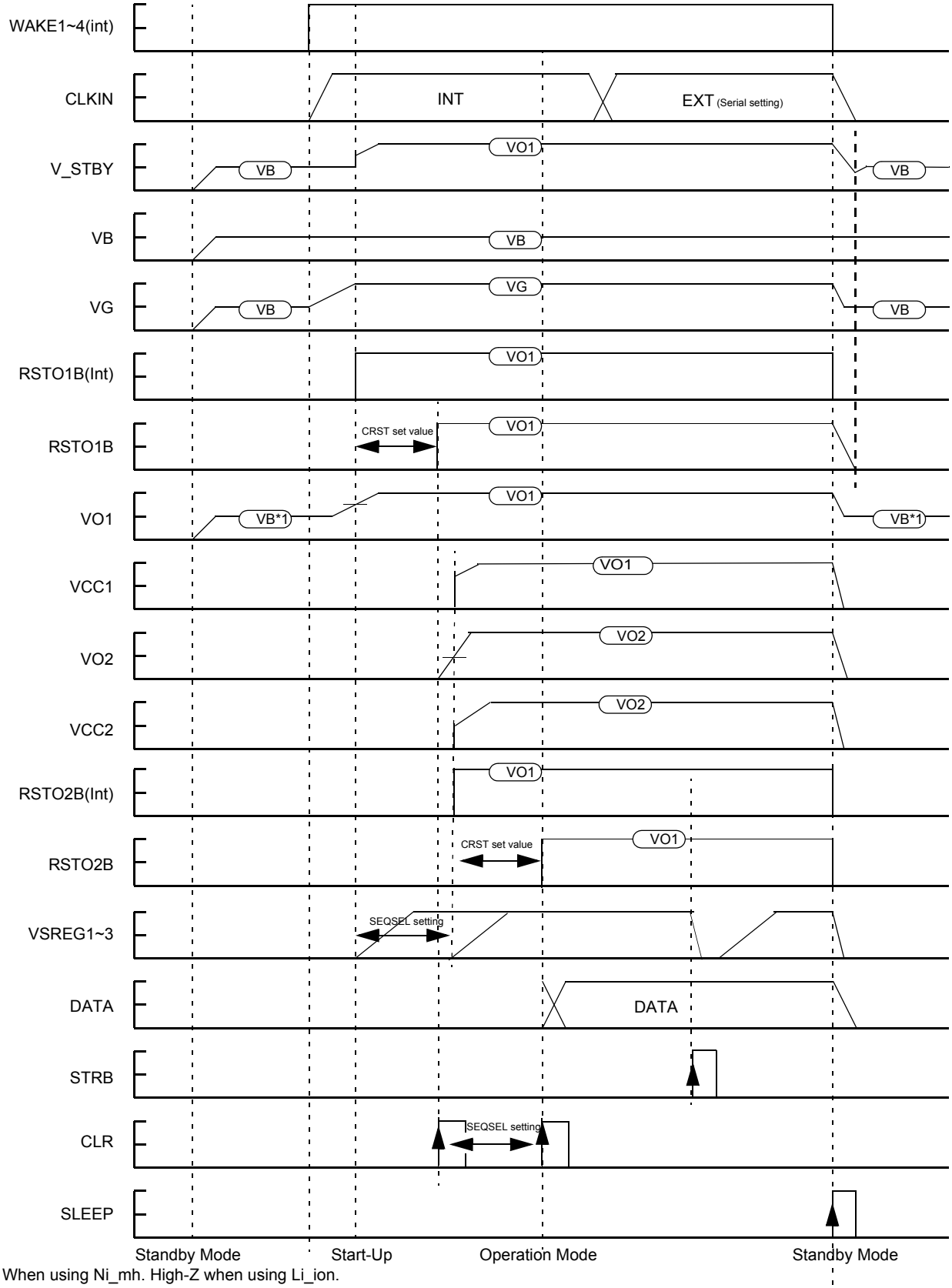
Characteristics noted under conditions V_B = 1.2 V, V_{O1} = 2.4 V, V_G = 6.0 V, f_{CLK} = 176.4 kHz unless otherwise noted. Typical values noted reflect the approximate parameter means at T_A = 27°C under nominal conditions unless otherwise noted.

Characteristic	Symbol	Min	Typ	Max	Unit
OSCILLATOR					
Internal Oscillation Frequency	f_{ICK}	150	200	250	kHz
MICRO CONTROLLER INTERFACE					
Clock Signal Input (27)	f_{CLK}	-	176.4	-	kHz
Serial Interface (Refer to Timing Chart below)					
DATA Set Up Time	t_s	20	-	-	nsec
DATA Hold Time	t_h	20	-	-	nsec
SCKIN Clock Frequency	f_{sck}	-	6.0	-	MHz
SCKIN 'H' Pulse Width	t_{wckh}	50	-	-	nsec
SCKIN 'L' Pulse Width	t_{wckl}	50	-	-	nsec
SCKIN Hold Time	t_{hck}	50	-	-	nsec
STRB Set Up Time	t_{ssb}	50	-	-	nsec
STRB Pulse Width	t_{wsb}	50	-	-	nsec

Notes

27. Duty 50%.

FUNCTIONAL DIAGRAMS



*1: When using Ni_mh. High-Z when using Li_ion.

Figure 4. Power Supply Start-Up Timing Diagram

18730

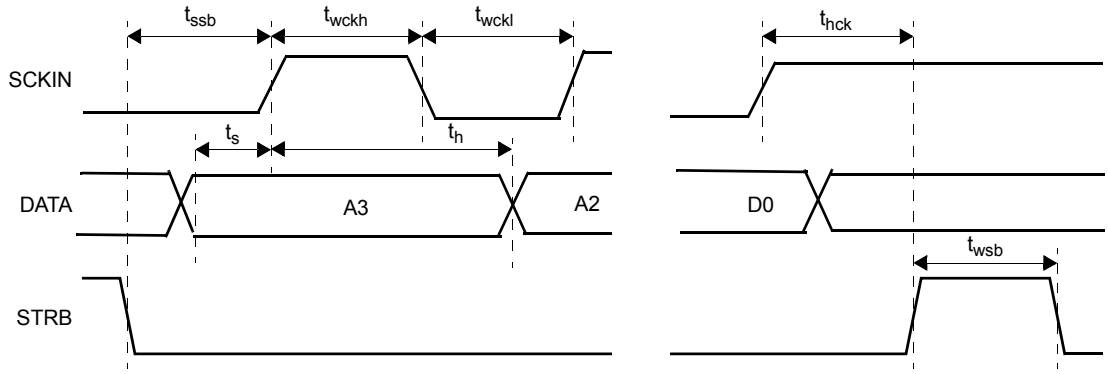


Figure 5. Serial Interface Timing Diagrams

Table 5. Serial Interface Functions

	Register Name	Address	DATA1				DATA2			
0	CLR, SLEEP	1000	CLR	SLEEP	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
1	Power Mode	0001	PSW1	PSW2	RSTO1B	VCC2	SREG1	SREG2	SREG3	RSTO2B
2	Clock Select	0010	Ext / Int	Half Freq	RSTB sleep	S_Off_VG	VG_Duty[3]	VG_Duty[2]	VG_Duty[1]	VG_Duty[0]
3	VO1	0011	MSB	VO1 Output Voltage					LSB	S_Off_VO1
4	VO2	0100	MSB	VO2 Output Voltage					LSB	S_Off_VO2
5	SREG1	0101	MSB	SREG1 Output Voltage					LSB	Reserved
6	SREG2	0110	MSB	SREG2 Output Voltage						LSB
7	SREG3	0111	MSB	SREG3 Output Voltage			LSB		CP Off	EXTG On

Twelve bits immediately before start-up of STRB are always effective. Upon power on, the internal power on reset works to initialize the registers. Serial data is fetched in the order of Add_[3], Add_[2], ..., Add_[0], DATA1_[3], DATA1_[2], ..., DATA2_[0].

Table 6. Block Operation

INPUT					OUTPUT				
WAKE(Int)	**RSTO1B(Int)**	**RSTO1B**	**RSTO2B(Int)**	**SEQSEL**	**VG**	**VO1**	**VO2**	**VCC1,2**	**REG1,2,3**
L	X	X	X	X	-	-	-	-	-
H	L	L	L	L	O	O	-	-	-
H	H	L	L	L	O	O	-	-	O
H	H	L	L	H	O	O	-	-	-
H	H	H	H	L	O	O	O	O	O
H	H	H	H	H	O	O	O	O	O

O : Operation, - : Stop, X : Don’t care

Table 7. Start-Up Sequence Settings

SEQSEL	CLR/SLEEP	Series Regulators
V_STBY	RSTO2B(Ext)	RSTO2B(Int)
GND	RSTO1B(Ext)	RSTO1B(Int)

FUNCTIONAL DESCRIPTION

INTRODUCTION

The 18730 power management integrated circuit provides five independent output voltages for the micro controller from either a single cell Li-Ion or from a single cell Ni-MH or dry cell. The PMIC includes two DC to DC converters and three low drop out linear regulators. The output voltage for each of the five output voltages is set independently through a 3-wire serial interface. The PMIC has multiple wakeup, sleep, and reset modes to minimize power consumption for portable equipment. In single cell Li-Ion applications two DC-DC converters are configured as buck regulators. In single cell Ni-MH or dry cell applications, one DC-DC converter is configured as a boost regulator, and the other as buck-boost regulator.

FUNCTIONAL TERMINAL DESCRIPTION

CLEAR TERMINAL (CLR)

This Clear input signal makes clear internal latches for WAKE signal holding. The WAKE control circuit can not receive another WAKE input until the latch is cleared by this Clear input.

WAKE SIGNAL TERMINALS (WAKE1B, WAKE2B, WAKE3B, WAKE4B) ... ACTIVE LOW

Any one WAKE input signal of these four WAKE inputs awakes this device from sleep mode. The WAKE signals can be made with external low side mechanical switch and resistance that is pulled up to VSTB rail.

LOW-SIDE SWITCH OUTPUT TERMINAL (LSWO)

Low-Side switch output that is turned on with ‘CLR’ signal. It can be used for external key input latches clear.

LOW VOLTAGE BATTERY TERMINAL (LVB)

This input terminal is used for temporarily power supply while wake up for 1cell Ni-MH battery or 1cell dry cell battery (= Low Voltage Battery) use. It has to be connected to VB rail. When Li-Ion battery is used, the terminal has to be open.

HIGH VOLTAGE BATTERY TERMINAL (HVB)

This input terminal is used for temporarily power supply while wake up for Li-Ion battery (= High Voltage Battery) use. It has to be connected to the VB rail. When a Ni-MH battery is used, the terminal has to be connected to ground level.

STANDBY VOLTAGE TERMINAL (V_STBY)

Standby Voltage is made from LVB or HVB that depends on which battery is used. This voltage is used for internal logic and analog circuit at standby (sleep) mode temporarily before ‘VO1’ voltage is established.

VOLTAGE INPUT TERMINALS (VO1, VO2)

This power supply input terminal named ‘VO1 or VO2’ is for internal logic and analog circuits and for input of ‘VCC1’ output via power switch. Input for ‘VCC2’ is ‘VO2IN’ terminal. It is supplied from the output of Channel-1 or Channel-2 DC/DC converter as ‘VO1 or VO2.

VOLTAGE OUTPUT TERMINALS (VCC1, VCC2)

Output ‘VO1’ or ‘VO2’ voltage controlled internal power switch.

POWER INPUT TERMINALS (VI1, VI2)

The power input terminals (VI1, VI2) are drain terminals on the top side FET of the DC/DC converter switcher. They are the power input for the buck converter and output for the boost converter.

SWITCHING TERMINALS (SW1, SW2)

Switching Terminals (SW1, SW2) are the output of the half bridge and connect to the external inductance.

POWER GROUND TERMINALS (PGND1, PGND2, PGND3)

Ground level node for DC/DC converter and Charge Pump portion.

INVERTED RESET OUTPUT TERMINALS (RSTO1B, RSTO2B)

Reset signal output for external MPU or the something controller. RSTO1B keeps ‘Low’ level while the VO1 voltage is less than internal reference voltage. RSTO2B follows to VO2 voltage.

RESET DELAY CAPACITOR TERMINALS (CRST1, CSRT2)

The capacitor which is connected to this terminal decide delay time to negate Reset signal from exceeding the reference voltage level.

RESET 1 ADJUSTMENT TERMINAL (RST1ADJ)

Used to adjust the reset level with external resistance which is connected to VO1 for RSTO1B.

DUTY CONTROL TERMINALS (DTC1, DTC2)

Connected external voltage to this terminal via capacitance can control the duty of DC/DC converter switching. Use of the terminal for this is not recommended.

REFERENCE FEEDBACK TERMINALS (RF1, RF2)

Output node of internal error amp. for DC/DC converter 1 and 2. For phase compensation use.

INPUT MINUS TERMINALS (INM1, INM2)

Minus input of internal error amp. for DC/DC converter 1 and 2. For phase compensation use.

CHARGE PUMP CAPACITOR TERMINAL (C1L)

In case of use higher voltage than VG externally, connect capacitance and diodes between VG. The charge pump structure can output VG + VB - 2 x VF voltage. There is no meaning for Ni-MH or dry cell battery, because the VB voltage is almost same as 2 x VF voltage. Recommend to use for Li-Ion battery use.

GATE VOLTAGE TERMINAL (VG)

Output terminal of boost converter for gate drive voltage. The output voltage is decided by VGSEL input.

SWITCHING FOR GATE VOLTAGE TERMINAL (SWG)

Switching terminal for VG boost converter. Connect to external inductance.

BATTERY VOLTAGE TERMINAL (VB)

Power supply input that connects to Ni-MH or Dry cell or Li-Ion battery.

VG SELECT TERMINALS (VGSEL1, VGSEL2)

VG output voltage is decided with these two bits input.

VOLTAGE INPUT FOR POWER SWITCH 2 TERMINAL (VO2IN)

Input of VCC2 output via power switch. Connect to VO2 terminal externally.

STEP DOWN FET GATE DRIVE TERMINALS (DW_2T, DW_2B)

Gate drive output terminals for external FETs to use DC/DC converter 2 as Buck / Boost converter.

GATE SWITCH TERMINAL (EXT_G_ON)

Gate drive output terminal for external low side switch. It can be used for power switch turning On/OFF for remote controller part.

REGULATOR CONTROL TERMINALS (SREGC1, SREGC2, SREGC3)

Feed back terminal for each series regulators. This terminal voltage is compared with internal reference voltage. Input the feed back voltage that divided SREGO voltage by resistances.

REGULATOR OUTPUT TERMINALS (SREGO1, SREGO2, SREGO3)

Series regulator output terminals. All output voltages can be variable with internal DAC via serial I/F.

REGULATOR INPUT TERMINALS (SREGI1, SREGI2, SREGI3)

Series regulator power input terminals. To be connected to battery voltage in general.

GROUND TERMINAL (GND)

Ground terminal for logic and analog circuit portion (not power portion). Recommend to connect to clean ground which separated with power ground line.

REFERENCE VOLTAGE TERMINAL (VREF)

Output of internal reference voltage. It can be used externally. Output current capacity is less than 300uA.

DATA INPUT TERMINAL (DATA)

Serial data input terminal. The latest 12 bits before strobe signal are valid.

STROBE TERMINAL (STRB)

Strobe signal input terminal for serial I/F. It establishes the input 12bits data to internal control registers.

SERIAL CLOCK TERMINAL (SCKIN)

Clock input terminal for serial I/F. Input data are taken in to I/F with this clock.

WATCH DOG TIMER TERMINAL (WDT)

Watch dog timer prevent unstable wake up (flips between wake-up and failure). If there is no ‘CLR’ input after any WAKEnB input before this WDT is expired, this device move to ‘SLEEP’ mode to prevent wake failure hanging-up situation.

SEQUENCE SELECT TERMINAL (SEQSEL)

Select judgement Reset channel for wake-up complete with this input. If this input level is VSTB voltage, this device judges the wake-up completion with Reset2 (DC/DC2). If it is Ground, judge with Reset1 (DC/DC1). See Table 7, on page 13.

CLOCK INPUT TERMINAL (CLKIN)

Clock input terminal for internal switching part. This device has a oscillator internally, but can be used this input clock for internal switching frequency. It is selected by Clock select bit. See Table 19, on page 26.

SLEEP MODE TERMINAL (SLEEP)

The sleep input signal puts the device in sleep mode. All output voltages are down, and internal current consumption will be minimum.

FUNCTIONAL DEVICE OPERATION

OPERATIONAL MODES

START-UP CONTROL INPUT (SYSTEM CONTROL)

The latch is set at the rising edge of any WAKE1B-4B input pin, and WAKE(int) goes High. WAKE1~4B inputs consist of OR logic. At this time, the input pin which went Low keeps latched until CLR goes High. After the latch is reset by CLR, WAKE(int) goes Low when SLEEP goes High. The latch is also cleared and WAKE(int) goes Low when SLEEP goes High before the latch is cleared by CLR. In this case, CLR keeps negated while RSTO1B, 2B(Ext) is Low. SLEEP keeps negated while RSTO1B, 2B(Ext) is Low or CLR is High. The period of time for which CLR and SLEEP are negated can be set by the SEQSEL pin. Refer to Truth Table 5, on page 13 for the correspondence between the SEQSEL pin settings and negation period.

If SLEEP goes High to place the chip into the standby mode while any of the WAKEB pins is Low, the chip can be awakened again. This may happen if, when an WAKEB pin and LSWO are connected, SLEEP goes High earlier than the period of time (*1) specified by the external component of the WAKEB pin.

Also, if the period of time after WAKE(int) goes High until CLR goes High from Low is longer than the time specified by WDT, internal sleep will start up to place the chip into the standby mode.

(*1: It is 30 µsec when a capacitor is not connected as the external component.)

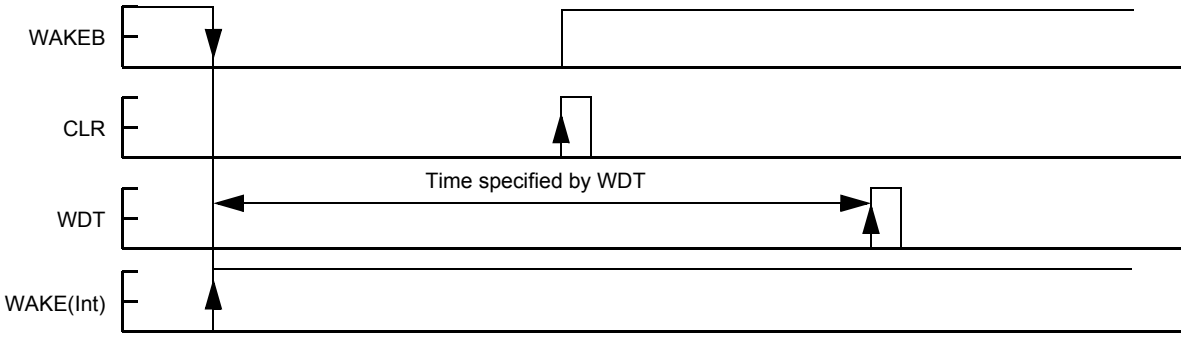


Figure 6. Start-Up Timing Diagram

STANDBY POWER SUPPLY CIRCUIT

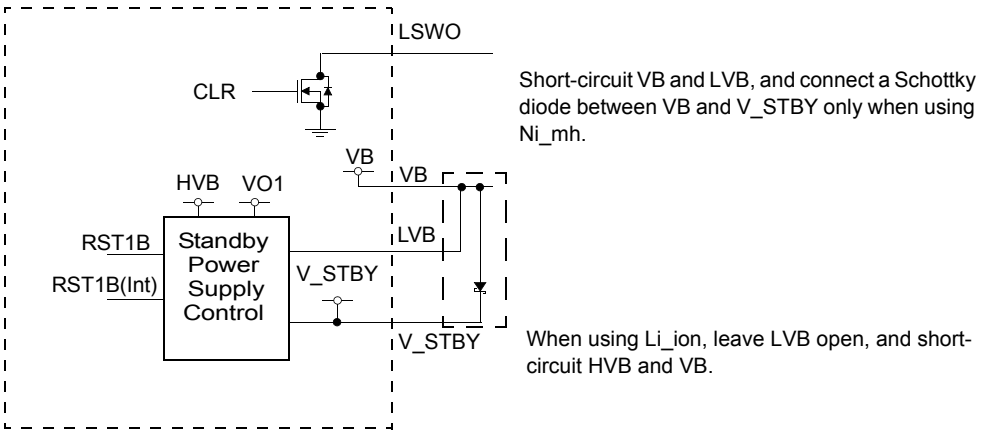


Figure 7. Standby Power Supply Circuit Diagram

When RSTO1B(int) is Low, output LVB voltage to V_STBY terminal. When RSTO1B(int) is High, output VO1 voltage to V_STBY terminal. When CLR is Low, LSWO is open. When RSTO1B(int) is High and CLR is High, LSWO output voltage turns GND. When RSTO1B(int) is Low and RSTO1B is High, discharge the external capacitor which is connected to V_STBY. When using Ni_mh, short-circuit VB and LVB to external components and HVB to GND. When using Li_ion, short-circuit HVB to VB, and leave LVB open. When using Ni_MH, the VB voltage is output from V_STBY in Standby mode. When using Li-Ion, 50% of the VB voltage is output to V_STBY terminal in Standby Mode.

Table 8. HVB and LVB Connection

MODE	HVB	LVB
Li_ion	VB[28]	open
Ni_mh	GND	VB[28]

Notes
28. Externally connect to VB.

Table 9. V_STBY and LSWO Operation

INPUT			OUTPUT	
WAKE(Int)	RSTO1B(Int)	CLR	V_STBY	LSWO
L	X	X	VB	Z
H	L	X	VB	Z
H	H	L	VO1	Z
H	H	H	VO1	L

Z : High Impedance, X : Don't care

RESET CIRCUIT

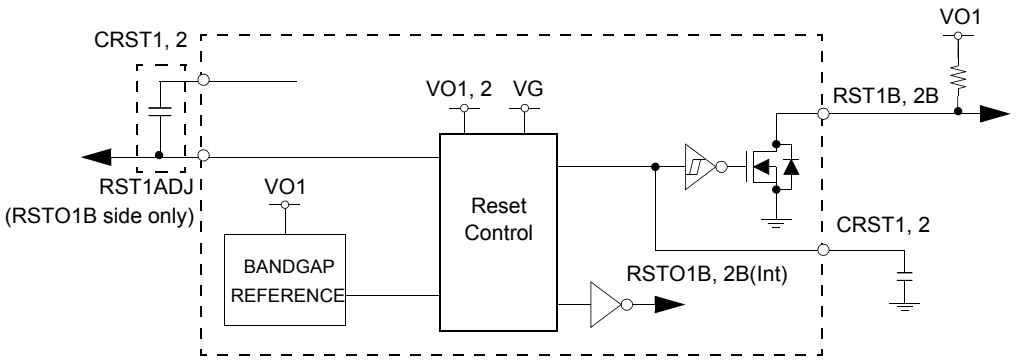


Figure 8. Reset Circuit Block Diagram

When the VO1 or VO2 voltage is higher than the reference value, RSTO1B or 2B goes High. When RSTO1B(int) is Low and RSTO1B is High, SLEEP(int) is forced to place the chip into the standby mode.

Connect a capacitor between RST1ADJ and CRST. The capacitor is not necessary if a resistor of 330KΩ or less is inserted between RST1ADJ and VC1 for reset adjustment

Connect the capacitor between RST1ADJ and RSTB as directed below.

When SEQSEL is Low: Between RST1ADJ and CRST1

When SEQSEL is High: Between RST1ADJ and CRST2

Use a capacitor with approximately half of the capacitance between CRST and GND

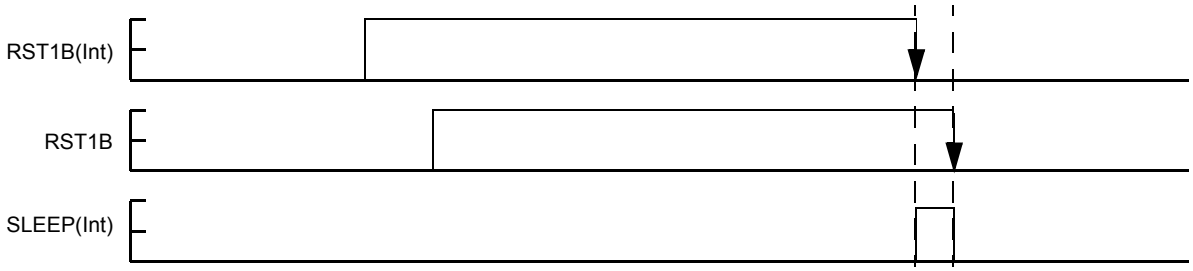


Figure 9. Reset Timing Diagram

POWER SUPPLY VO1, VO2: NI_MH

The VB voltage rises and is output to VI1. When RSTO2B(int) is High, the power switch turns ON to output the VO1 voltage to VCC1. Capacitance value which is connected to VO1 should be higher than the capacitor connected to VCC1.

The VB voltage rises or falls and is output to VI2. When RSTO2B(int) is High, the power switch turns ON to output the VO2IN voltage to VCC2. If you turn DDC2 OFF using the register, the power switch 2 also turns OFF. Capacitance value which is connected to VO2IN should be higher than the capacitor connected to VCC2.

Table 10. Output Voltage of VO1

Address : 0011(30)								
B7	**B6**	**B5**	**B4**	**B3**	**B2**	**B1**	**S_Off_VO1**	**VO1 [V]**(29)
L	L	L	L	L	L	L	X	1.613
L	L	L	L	L	L	H	X	1.625
L	L	L	L	L	H	L	X	1.638
L	L	L	L	H	L	L	X	1.663
L	L	L	H	L	L	L	X	1.713
L	L	H	L	L	L	L	X	1.813
L	H	L	L	L	L	L	X	2.013
H	L	L	L	L	L	L	X	2.413
H	L	L	L	L	L	H	X	2.425
H	L	L	L	L	H	L	X	2.438
H	L	L	L	H	L	L	X	2.463
H	L	L	H	L	L	L	X	2.513
H	L	H	L	L	L	L	X	2.613
H	H	L	L	L	L	L	X	2.813
H	H	H	H	H	H	H	X	3.200

Notes

29. Operation is not guaranteed when VO1 input voltage is 1.8 V or lower. By connecting a diode between VI1 and VO1, VI1 can output voltage higher (with the voltage difference Vf) than VO1.
30. All combinations of input are not included.

Table 11. Output Voltage of VO2

Address : 0100(31)								
B7	**B6**	**B5**	**B4**	**B3**	**B2**	**B1**	**S_Off_VO2**	**VO2 [V]**
L	L	L	L	L	L	L	X	0.805
L	L	L	L	L	L	H	X	0.811
L	L	L	L	L	H	L	X	0.816
L	L	L	L	H	L	L	X	0.827
L	L	L	H	L	L	L	X	0.849
L	L	H	L	L	L	L	X	0.893
L	H	L	L	L	L	L	X	0.980
H	L	L	L	L	L	L	X	1.155
H	L	L	L	L	L	H	X	1.161
H	L	L	L	L	H	L	X	1.166
H	L	L	L	H	L	L	X	1.177
H	L	L	H	L	L	L	X	1.199
H	L	H	L	L	L	L	X	1.243
H	H	L	L	L	L	L	X	1.330
H	H	H	H	H	H	H	X	1.500

Notes

31. All combinations of input are not included.

POWER SUPPLY VO1, VO2: LI-ION

The VB voltage falls and is output to VO1. When using Li_ion, duty limit due to DTC1 is not applied to the switch. When RSTO2B(int) is High, the power switch turns ON to output the VO1 voltage to VCC1. Capacitance value which is connected to VO1 should be higher than the capacitor connected to VCC1.

The VB voltage falls using only the internal transistor and is output to VO2. When using Li_ion, duty limit due to DTC2 is not applied to the switch, and DW_2T and DW_2B are Low. When RSTO2B(int) is High, the power switch turns ON to output the VO2IN voltage to VCC2. If you turn DDC2 OFF using the register, the power switch 2 also turns OFF. Capacitance value which is connected to VO2IN should be higher than the capacitor connected to VCC2.

SERIES PASS POWER SUPPLY

The series pass outputs the SREGI1 voltage to SREGO1, the SREGI2 voltage to SREGO2, and the SREGI3 voltage to SREGO3. If you use MOSFET as the external component in this case, connect the gate to SREG2G.

Table 12. Output Voltage of SREG1

Address : 0101(31)								
B7	**B6**	**B5**	**B4**	**B3**	**B2**	**B1**	**Reserved**	**SREG1 [V]**(32)
L	L	L	L	L	L	L	H	0.865
L	L	L	L	L	L	H	H	0.880
L	L	L	L	L	H	L	H	0.895
L	L	L	L	H	L	L	H	0.926
L	L	L	H	L	L	L	H	0.986
L	L	H	L	L	L	L	H	1.107
L	H	L	L	L	L	L	H	1.349
H	L	L	L	L	L	L	H	1.833
H	L	L	L	L	L	H	H	1.848
H	L	L	L	L	H	L	H	1.863
H	L	L	L	H	L	L	H	1.893
H	L	L	H	L	L	L	H	1.954
H	L	H	L	L	L	L	H	2.075
H	H	L	L	L	L	L	H	2.317
H	H	H	H	H	H	H	H	2.800

Notes

32. The SREG1 and 3 output voltages are determined by the combination of external resistances connected to REGC1 and 3 (65.14KΩ between SREGO1 and REGC1, 34.86KΩ between REGC1 and GND, 73.84KΩ between SREGO3 and REGC3, and 26.16KΩ between REGC3 and GND).
33. All combinations of input are not included.

Table 13. Output Voltage of SREG2

Address : 0110(31)								
B7	**B6**	**B5**	**B4**	**B3**	**B2**	**B1**	**B0**	**SREG2 [V]**
L	L	L	L	L	L	L	L	0.011
L	L	L	L	L	L	L	H	0.022
L	L	L	L	L	L	H	L	0.033
L	L	L	L	L	H	L	L	0.055
L	L	L	L	H	L	L	L	0.098
L	L	L	H	L	L	L	L	0.186
L	L	H	L	L	L	L	L	0.361
L	H	L	L	L	L	L	L	0.711
H	L	L	L	L	L	L	L	1.411
H	L	L	L	L	L	L	H	1.422
H	L	L	L	L	L	H	L	1.433
H	L	L	L	L	H	L	L	1.455
H	L	L	L	H	L	L	L	1.498
H	L	L	H	L	L	L	L	1.586
H	L	H	L	L	L	L	L	1.761
H	H	L	L	L	L	L	L	2.111
H	H	H	H	H	H	H	H	2.800

Notes

34. All combinations of input are not included.

Table 14. Output Voltage of SREG3

Address : 0111(31)								
B7	**B6**	**B5**	**B4**	**B3**	**B2**	**CP Off**	**EXTG On**	**SREG3 [V]**(35)
L	L	L	L	L	L	X	X	2.080
L	L	L	L	L	H	X	X	2.091
L	L	L	L	H	L	X	X	2.102
L	L	L	H	L	L	X	X	2.125
L	L	H	L	L	L	X	X	2.170
L	H	L	L	L	L	X	X	2.260
H	L	L	L	L	L	X	X	2.440
H	L	L	L	L	H	X	X	2.451
H	L	L	L	H	L	X	X	2.462
H	L	L	H	L	L	X	X	2.485
H	L	H	L	L	L	X	X	2.530
H	H	L	L	L	L	X	X	2.620
H	H	H	H	H	H	X	X	2.800

Notes

35. The SREG1 and 3 output voltages are determined by the combination of external resistances connected to REGC1 and 3 (65.14KΩ between SREGO1 and REGC1, 34.86KΩ between REGC1 and GND, 73.84KΩ between SREGO3 and REGC3, and 26.16KΩ between REGC3 and GND).
36. All combinations of input are not included.

VG GENERATOR

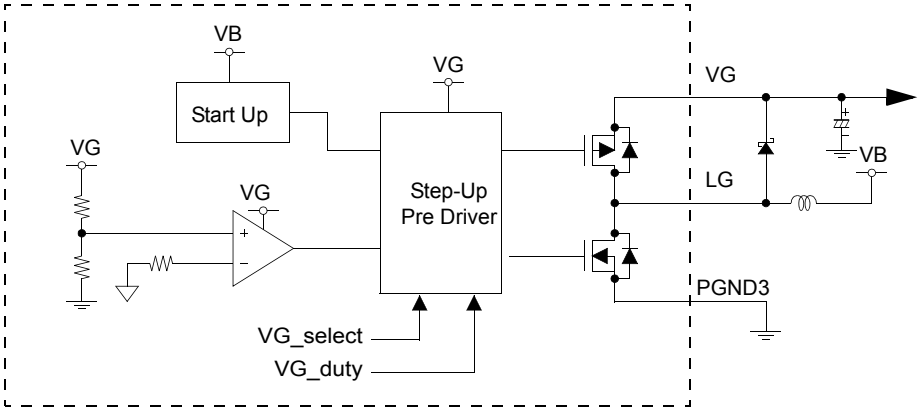


Figure 10. Circuit when using a Step-Up Converter

When WAKE (int) goes High from Low, the start-up circuit raises the VB voltage and outputs it to VG, then outputs the VG voltage when RSTO1B (int) goes High. The charge pump circuit can be used for both Ni_mh and Li_ion by setting the necessary registers. The charge pump circuit is disabled by default.

The VG voltage can be set to 6 V to 4.5 V according to the combination of VGSEL1 and 2 pin connections. Refer to Table 16, VG Voltage Settings and VGSEL1 and 2 Pin Connection on page 24 for the VG voltage settings.

When using a charge pump, please refer to Figure 11.

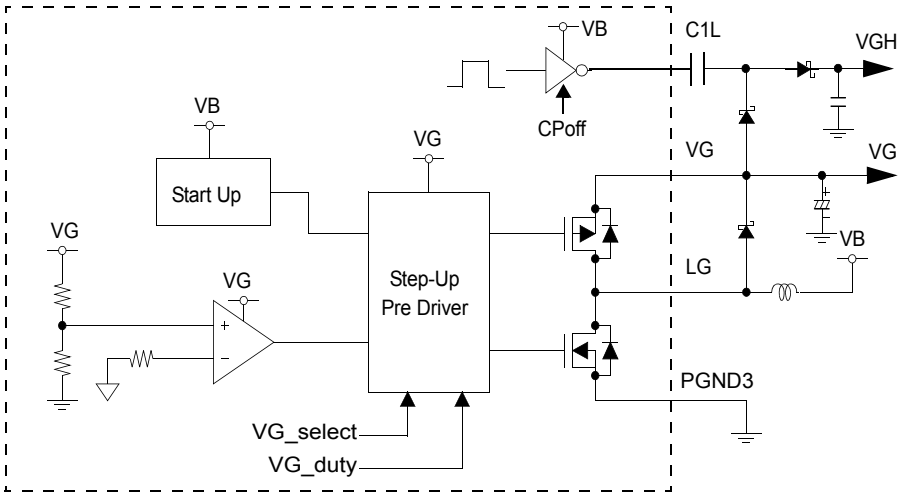


Figure 11. Circuit When Using a Charge Pump

Table 15. VG Duty Settings

Address : 0010								
Ext/Int	**Half Freq**	**RSTB sleep**	**S_Off_VG**	**VG_Duty[3]**	**VG_Duty[2]**	**VG_Duty[1]**	**VG_Duty[0]**	**Duty**
X	X	X	X	L	L	L	L	90 %
X	X	X	X	L	L	L	H	86 %
X	X	X	X	L	L	H	L	82 %
X	X	X	X	L	H	L	L	74 %
X	X	X	X	H	L	L	L	58 %
X	X	X	X	H	L	L	H	54 %
X	X	X	X	H	L	H	L	50 %
X	X	X	X	H	H	L	L	42 %
X	X	X	X	H	H	H	H	30 %

Table 16. VG Voltage Settings and VGSEL1 and 2 Pin Connection

VGSEL1	VGSEL2	VG [V]
GND	GND	6.0
GND	VB	5.5
VB	GND	5.0
VB	VB	4.5

LOGIC COMMANDS AND REGISTERS

REGISTER MAPPINGS

Table 17. CLR and SLEEP Control Register

1000	Data1				Data2			
Bit	3	2	1	0	3	2	1	0
Name	CLR	SLEEP	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Default	0	0	0	0	0	0	0	0

CLR : CLR Control
1 = CLR is high
0 = CLR is low

SLEEP : SLEEP Control
1 = SLEEP is high
0 = SLEEP is low

Reserved : Freescale defined register *1
1 = Forbidden
0 = Required

Reserved : Freescale defined register *1
1 = Forbidden
0 = Required

Reserved : Freescale defined register *1
1 = Forbidden
0 = Required

Reserved : Freescale defined register *1
1 = Forbidden
0 = Required

Reserved : Freescale defined register *1
1 = Forbidden
0 = Required

Reserved : Freescale defined register *1
1 = Forbidden
0 = Required

Reserved : Freescale defined register *1
1 = Forbidden
0 = Required

Note : Do NOT change Reserved Register from default value.

*1: Data write to this address (1000) is allowed for the most significant two bits only. The least significant 6 bits are only used for the factory test. When writing data, always write 0 to these six bits.

Table 18. Power Mode Register

0001	Data1				Data2			
Bit	3	2	1	0	3	2	1	0
Name	PSW1	PSW2	RSTO1B	VCC2	SREG1	SREG2	SREG3	RSTO2B
Default	1	1	0	1	1	1	1	0

PSW1 : VCC1 Power Switch control
1 = Power Switch on
0 = Power Switch off

PSW2 : VCC2 Power Switch control
1 = Power Switch on
0 = Power Switch off

RSTO1B : RSTO1B Mask *1
1 = RSTO1B mask on
0 = RSTO1B mask off

VO2 : DC/DC Converter Channel 2 output Control *2
1 = DDC2 on
0 = DDC2 off

SREG1 : Series Pass Regulator Channel1 output Control
1 = Regulator on
0 = Regulator off

SREG2 : Series Pass Regulator Channel2 output Control *3
1 = Regulator off
0 = Regulator on

SREG3 : Series Pass Regulator Channel3 output Control
1 = Regulator on
0 = Regulator off

RSTO2B : RSTO2B Mask *1
1 = RSTO2B mask on
0 = RSTO2B mask off

*1: When switching the output voltage of VO1 (2), write 1 to the RSTO1B (2) Mask bit in advance to fix the rest output to High for preventing erroneous operation.

*2: When turning DDC2 OFF, set the RSTO2B bit to High to Mask RSTO2B. If you turn DDC2 OFF, the power switch 2 also turns OFF.

Table 19. Clock Select Register

0010	Data1				Data2			
Bit	3	2	1	0	3	2	1	0
Name	Ext/Int	Half Freq	RSTB sleep	S_Off_VG	VG_Duty [3]	VG_Duty[2]	VG_Duty[1]	VG_Duty[0]
Default	0	0	1	0	0	0	0	0

Ext / Int : Clock Select control 1
1 = External Clock
0 = Internal Clock

2FS : Clock Select control 2
1 = 2FS on
0 = 2FS off

RSTB Sleep : RSTB Sleep Monitor *1
1 = RSTB SLEEP Monitor off
0 = RSTB SLEEP Monitor on

S_Off_VG : VG Top side transistor off
1 = Synchronous Rectification Off
0 = Synchronous Rectification On

VG_Duty[3] : VG Duty Control MSB
1 = VG Duty[3] is high
0 = VG Duty[3] is low

VG_Duty[2] : VG Duty Control Bit 2
1 = VG Duty[2] is high
0 = VG Duty[2] is low

VG_Duty[1] : VG Duty Control Bit1
1 = VG Duty[1] is high
0 = VG Duty[1] is low

VG_Duty[0] : VG Duty Control LSB
1 = VG Duty[0] is high
0 = VG Duty[0] is low

VG is controlled by PFM method. This register can change the duty by 16 steps.

Refer to Table 15, VG Duty Settings on page 24 for the correspondence between the VG Duty maximum values and register settings.

Table 20. VO1 Output Voltage Register

0011	Data1				Data2			
Bit	3	2	1	0	3	2	1	0
Name	VO1_V[6]	VO1_V[5]	VO1_V[4]	VO1_V[3]	VO1_V[2]	VO1_V[1]	VO1_V[0]	S_Off_VO1
Default	1	0	0	0	0	0	0	0

VO1_V[6] : Reference DAC MSB
1 = VO1_V[6] on
0 = VO1_V[6] off

VO1_V[5] : Reference DAC Bit5
1 = VO1_V[5] on
0 = VO1_V[5] off

VO1_V[4] : Reference DAC Bit4
1 = VO1_V[4] on
0 = VO1_V[4] off

VO1_V[3] : Reference DAC Bit3
1 = VO1_V[3] on
0 = VO1_V[3] off

VO1_V[2] : Reference DAC Bit2
1 = VO1_V[2] on
0 = VO1_V[2] off

VO1_V[1] : Reference DAC Bit1
1 = VO1_V[1] on
0 = VO1_V[1] off

VO1_V[0]: Reference DAC LSB
1 = VO1_V[0] on
0 = VO1_V[0] off

S_Off_VO1 : DDC1 Top side (Ni_mh) / Bottom side (Li_ion) transistor off
1 = Synchronous Rectification Off
0 = Synchronous Rectification On

Refer to Table 10, Output Voltage of VO1 on page 19 for the correspondence between the output voltage and register settings.

Table 21. VO2 Output Voltage Register

0100	Data1				Data2			
Bit	3	2	1	0	3	2	1	0
Name	VO2_V[6]	VO2_V[5]	VO2_V[4]	VO2_V[3]	VO2_V[2]	VO2_V[1]	VO2_V[0]	S_Off_VO2
Default	1	0	0	0	0	0	0	0

VO2_V[6] : Reference DAC MSB
1 = VO2_V[6] on
0 = VO2_V[6] off

VO2_V[5] : Reference DAC Bit5
1 = VO2_V[5] on
0 = VO2_V[5] off

VO2_V[4] : Reference DAC Bit4
1 = VO2_V[4] on
0 = VO2_V[4] off

VO2_V[3] : Reference DAC Bit3
1 = VO2_V[3] on
0 = VO2_V[3] off

VO2_V[2] : Reference DAC Bit2
1 = VO2_V[2] on
0 = VO2_V[2] off

VO2_V[1] : Reference DAC Bit1
1 = VO2_V[1] on
0 = VO2_V[1] off

VO2_V[0]: Reference DAC LSB
1 = VO2_V[0] on
0 = VO2_V[0] off

S_Off_VO2 : DDC2 Top side & DW2B (Ni_mh) / Bottom side (Li_ion) transistor off
1 = Synchronous Rectification Off
0 = Synchronous Rectification On

Refer to Table 11, Output Voltage of VO2 on page 20 for the correspondence between the output voltage and register settings.

Table 22. Regulator1 Output Voltage Register

0101	Data1				Data2			
Bit	3	2	1	0	3	2	1	0
Name	SREG1_V[6]	SREG1_V[5]	SREG1_V[4]	SREG1_V[3]	SREG1_V[2]	SREG1_V[1]	SREG1_V[0]	Reserved
Default	1	1	1	1	1	1	1	1

SREG1_V[6] : Reference DAC MSB
1 = SREG1_V[6] on
0 = SREG1_V[6] off

SREG1_V[5] : Reference DAC Bit5
1 = SREG1_V[5] on
0 = SREG1_V[5] off

SREG1_V[4] : Reference DAC Bit4
1 = SREG1_V[4] on
0 = SREG1_V[4] off

SREG1_V[3] : Reference DAC Bit3
1 = SREG1_V[3] on
0 = SREG1_V[3] off

SREG1_V[2] : Reference DAC Bit2
1 = SREG1_V[2] on
0 = SREG1_V[2] off

SREG1_V[1] : Reference DAC Bit1
1 = SREG1_V[1] on
0 = SREG1_V[1] off

SREG1_V[0]: Reference DAC LSB
1 = SREG1_V[0] on
0 = SREG1_V[0] off

Reserved : Blank register bit (Freescale Pre-Defined Register)
1 = Preferred
0 = Forbidden

Note : Do NOT change Reserved Register from default value.

Refer to Table 12, Output Voltage of SREG1 on page 21 for the correspondence between the output voltage and register settings.

Table 23. Regulator2 Output Voltage Register

0110	Data1				Data2			
Bit	3	2	1	0	3	2	1	0
Name	SREG2_V[7]	SREG2_V[6]	SREG2_V[5]	SREG2_V[4]	SREG2_V[3]	SREG2_V[2]	SREG2_V[1]	SREG2_V[0]
Default	1	1	1	1	1	1	1	1

SREG2_V[7]: Reference DAC MSB
1 = SREG2_V[7] on
0 = SREG2_V[7] off

SREG2_V[6] : Reference DAC Bit6
1 = SREG2_V[6] on
0 = SREG2_V[6] off

SREG2_V[5] : Reference DAC Bit5
1 = SREG2_V[5] on
0 = SREG2_V[5] off

SREG2_V[4] : Reference DAC Bit4
1 = SREG2_V[4] on
0 = SREG2_V[4] off

SREG2_V[3] : Reference DAC Bit3
1 = SREG2_V[3] on
0 = SREG2_V[3] off

SREG2_V[2] : Reference DAC Bit2
1 = SREG2_V[2] on
0 = SREG2_V[2] off

SREG2_V[1] : Reference DAC Bit1
1 = SREG2_V[1] on
0 = SREG2_V[1] off

SREG2_V[0]: Reference DAC LSB
1 = SREG2_V[0] on
0 = SREG2_V[0] off

Refer to Table 13, Output Voltage of SREG2 on page 22 for the correspondence between the output voltage and register settings.

Table 24. Regulator3 Output Voltage Register

0111	Data1				Data2			
Bit	3	2	1	0	3	2	1	0
Name	SREG3_V[5]	SREG3_V[4]	SREG3_V[3]	SREG3_V[2]	SREG3_V[1]	SREG3_V[0]	CP Off	EXTG On
Default	1	1	1	1	1	1	1	1

SREG3_V[5] : Reference DAC MSB
1 = SREG3_V[5] on
0 = SREG3_V[5] off

SREG3_V[4] : Reference DAC Bit4
1 = SREG3_V[4] on
0 = SREG3_V[4] off

SREG3_V[3] : Reference DAC Bit3
1 = SREG3_V[3] on
0 = SREG3_V[3] off

SREG3_V[2] : Reference DAC Bit2
1 = SREG3_V[2] on
0 = SREG3_V[2] off

SREG3_V[1] : Reference DAC Bit1
1 = SREG3_V[1] on
0 = SREG3_V[1] off

SREG3_V[0]: Reference DAC LSB
1 = SREG3_V[0] on
0 = SREG3_V[0] off

CP Off : Charge Pump Control
1 = Charge Pump off
0 = Charge Pump on

EXTG On : EXT_G_ON Control *
1 = EXT_G_ON is low (GND level)
0 = EXT_G_ON is high (VG level)

EXTG On Register is assumed to use Pch FET as external MOSFET.

If Nch FET will be used, Control logic should be inverted.

Refer to Table 14, Output Voltage of SREG3 on page 22 for the correspondence between the output voltage and register settings.

TYPICAL APPLICATIONS

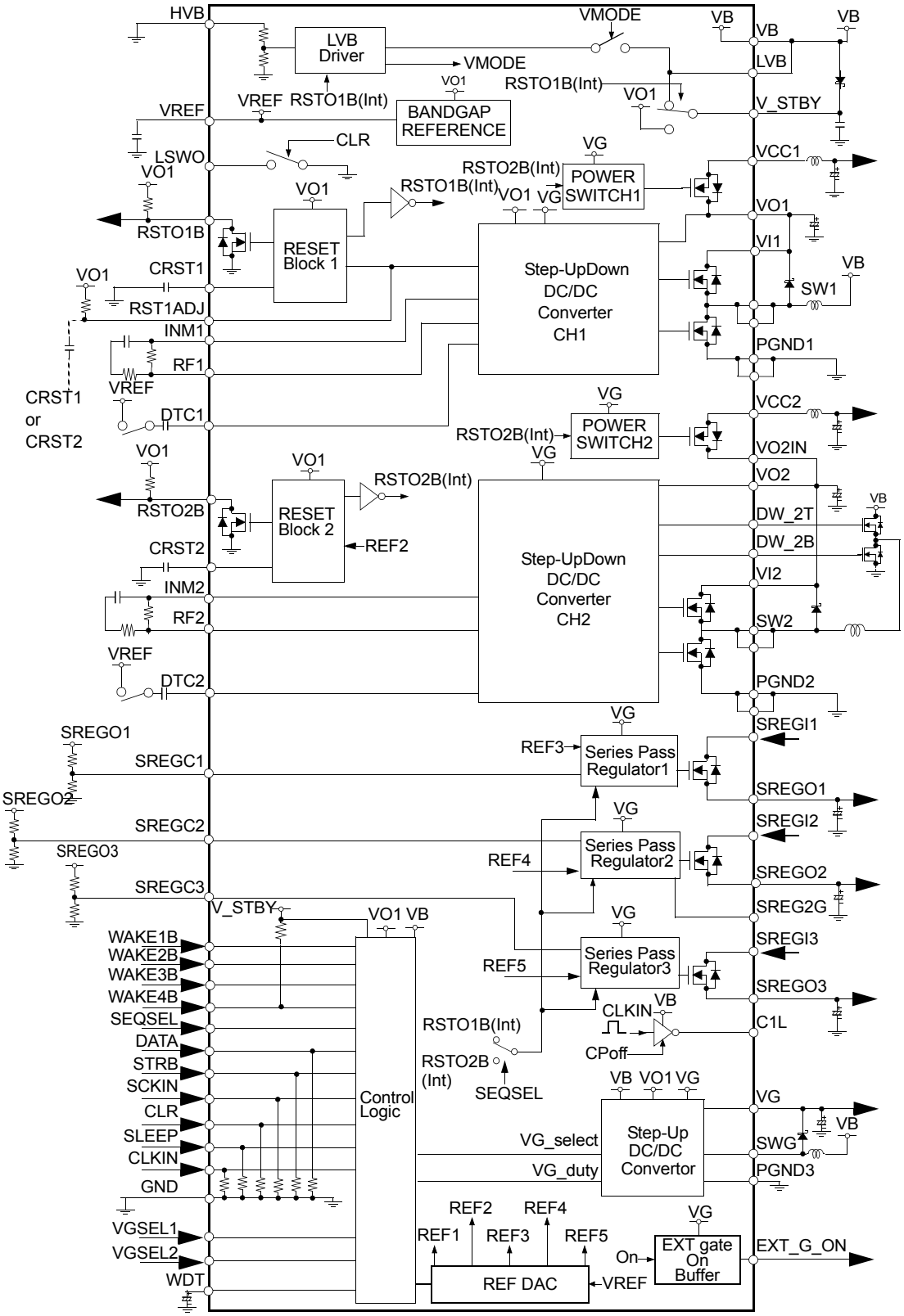


Figure 12. MPC18730 Typical Application Diagram (Ni-MH Battery)

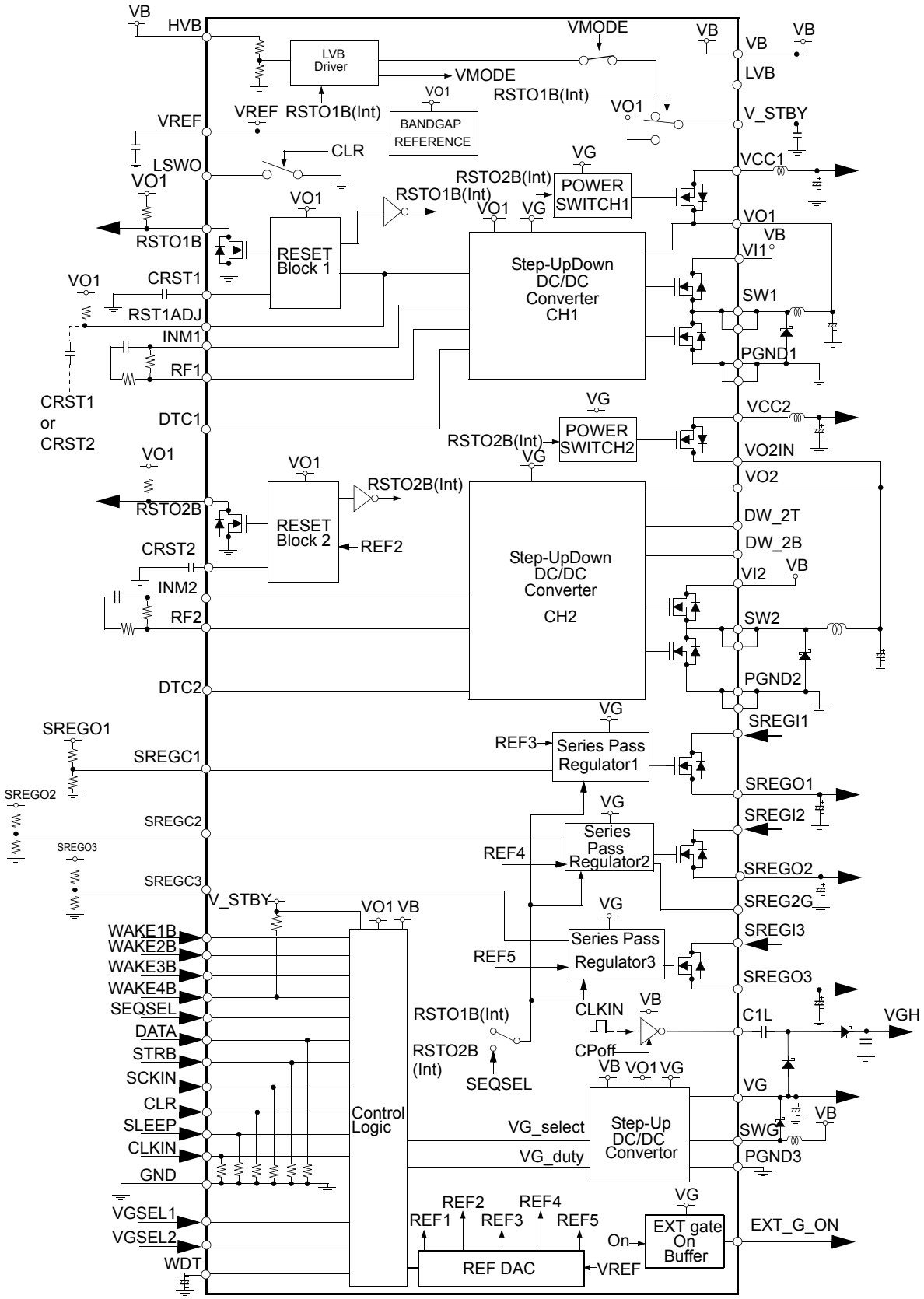
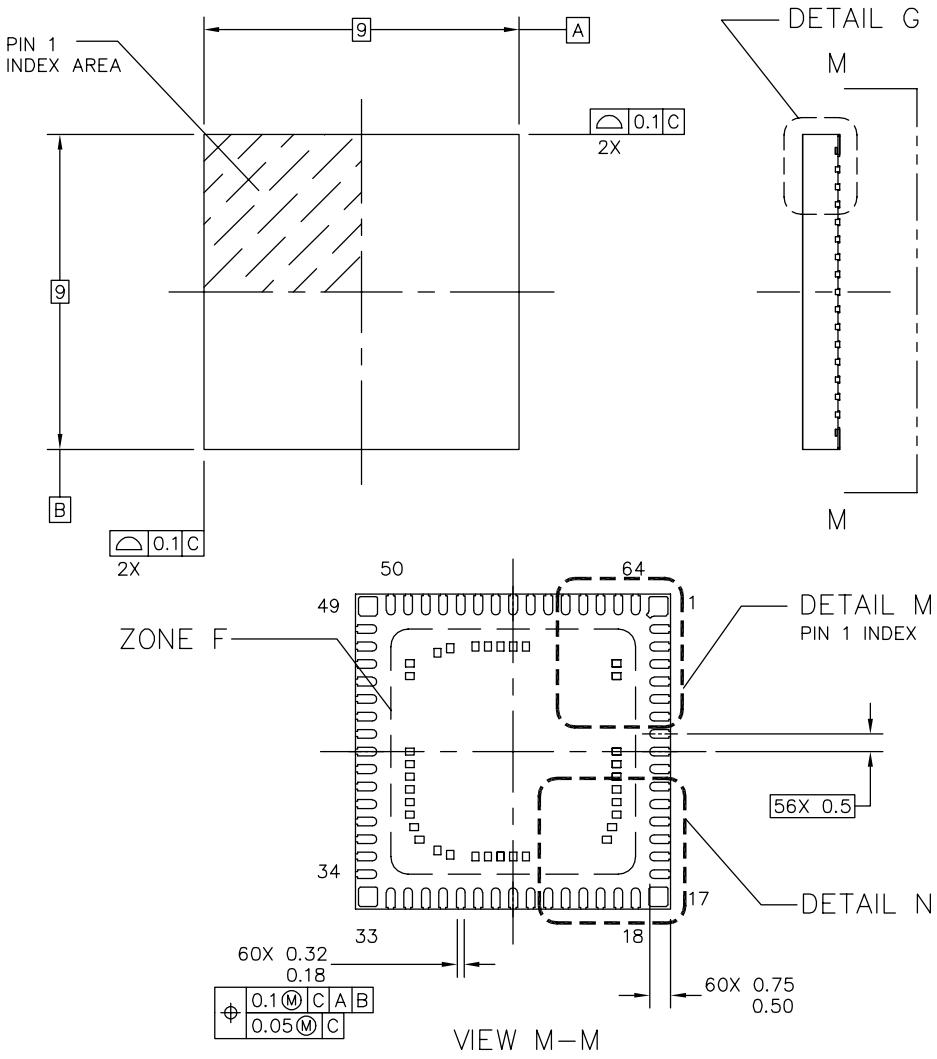


Figure 13. MPC18730 Typical Application Diagram (Li-Ion Battery)

PACKAGING

PACKAGE DIMENSIONS

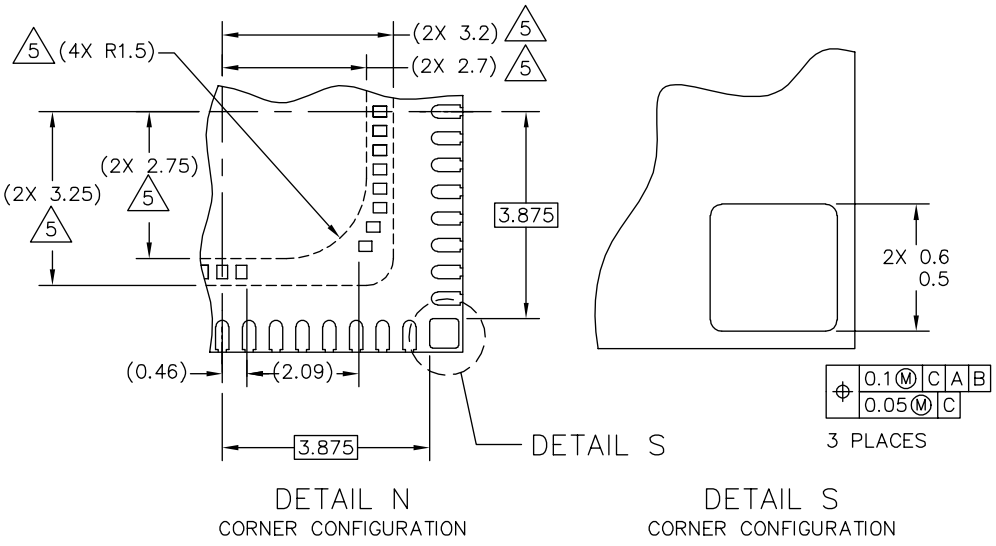
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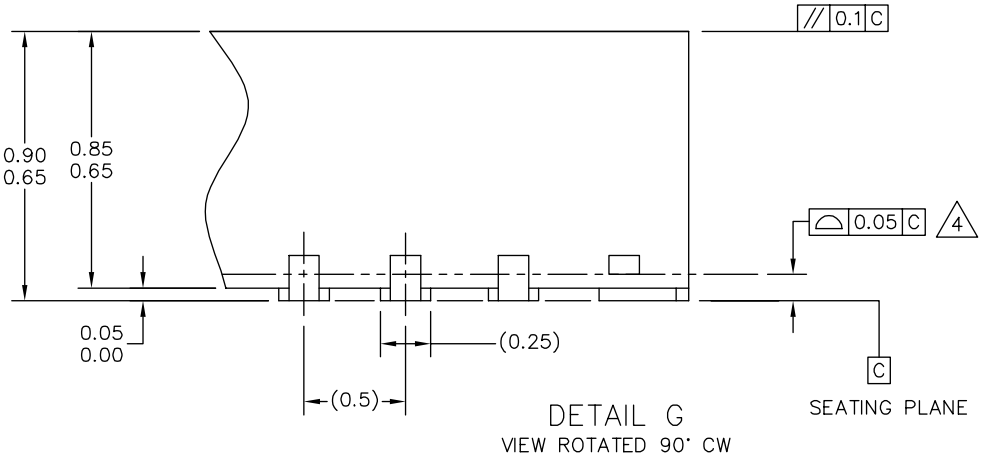


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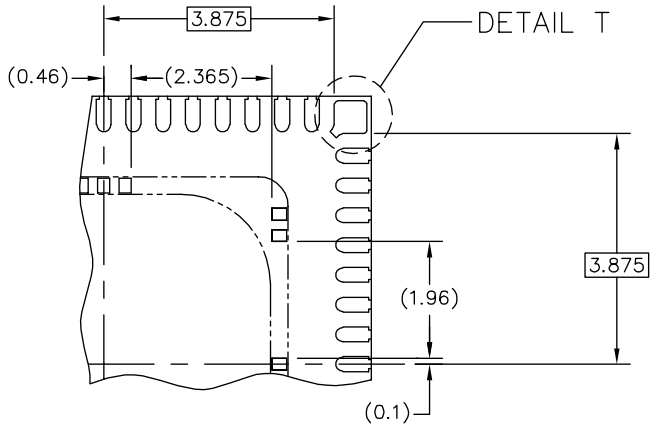




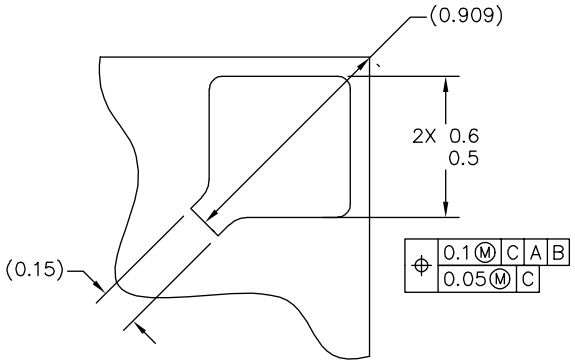
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DETAIL M
BACKSIDE PIN 1 INDEX

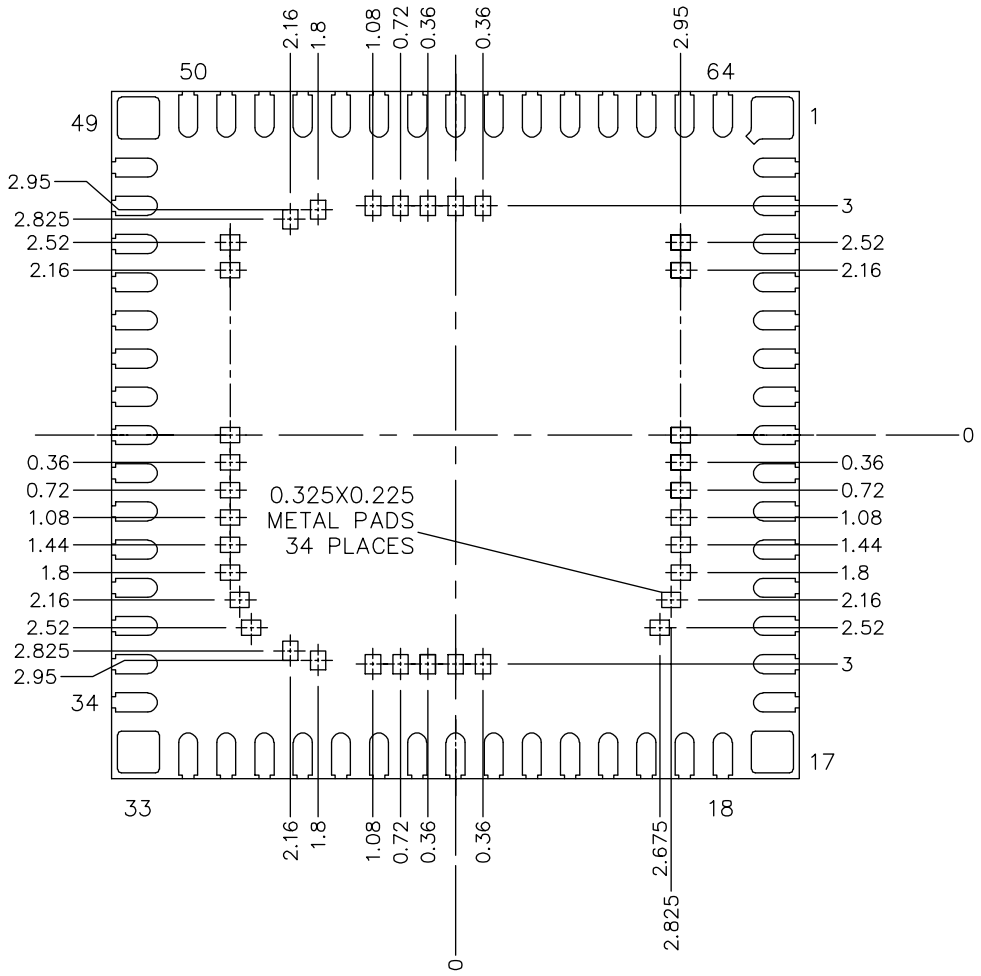


DETAIL T
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REVISION HISTORY

Revision	Date	Description of Changes
1.0	10/2005	• Initial Release

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